



SS22~SS2200

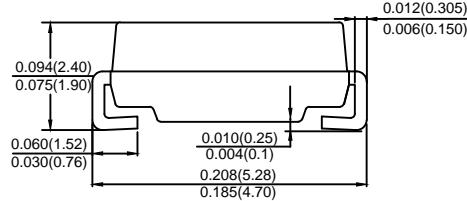
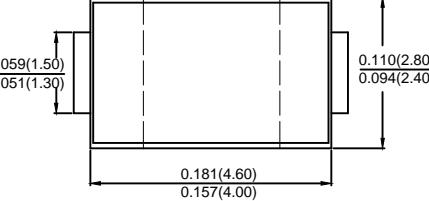
Surface Mount Schottky Rectifiers

Features

- Low profile package
- Ideal for automated placement
- Ultrafast reverse recovery time
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC

Mechanical Data

- **Case:** JEDEC DO-214AC (SMA) molded plastic
- **Terminals:** Solder plated, solderable per J-STD-002B and JESD22-B102D
- **Polarity:** Laser band denotes cathode end



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	SYMBOL	SS 22	SS 24	SS 26	SS 28	SS 210	SS 2150	SS 2200	Unit		
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	20	40	60	80	100	150	200	V		
Maximum RMS Voltage	V _{RMS}	14	28	42	56	70	105	140	V		
Maximum DC Blocking Voltage	V _{DC}	20	40	60	80	100	150	200	V		
Average Rectified Output Current @T _L =100°C	I _O	2.0						A			
Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	50						A			
Rating for fusing (t<8.3ms)	I ² t	10.37						A ² s			
Forward Voltage @IF=2.0A	V _{FM}	0.55		0.7		0.85		0.92		V	
Peak Reverse Current @T _A =25°C	I _R	0.1			0.05			mA			
At Rated DC Blocking Voltage @T _A =100°C		10			5						
Typical Junction Capacitance (Note 2)	C _J	150						pF			
Typical Thermal Resistance per leg	R _{θ JLA}	72						°C/W			
Operating Temperature Range	T _J	-55 to +150						°C			
Storage Temperature Range	T _{STG}	-55 to +150						°C			

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GUANGDONG JUXING ELECTRONIC TECHNOLOGY., LTD



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Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

Fig. 1 Forward Current Derating Curve

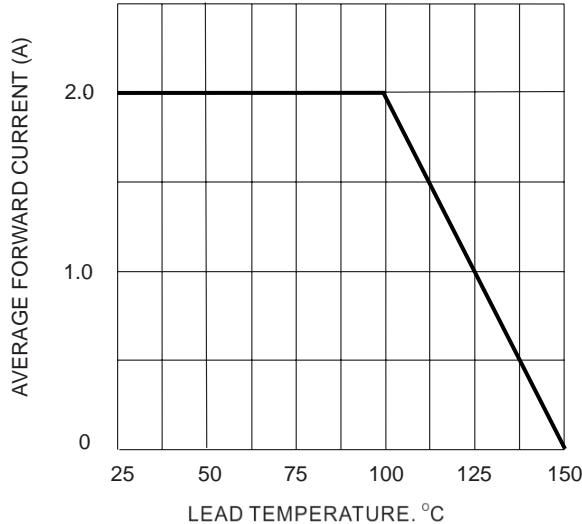


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

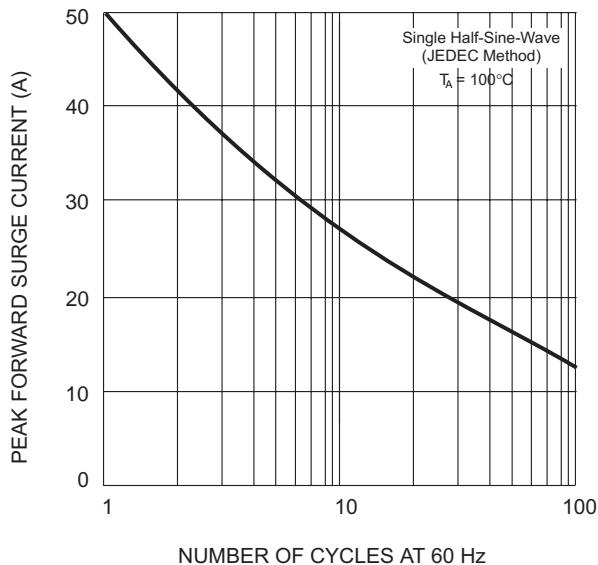


Fig. 2 Typ. Forward Characteristics

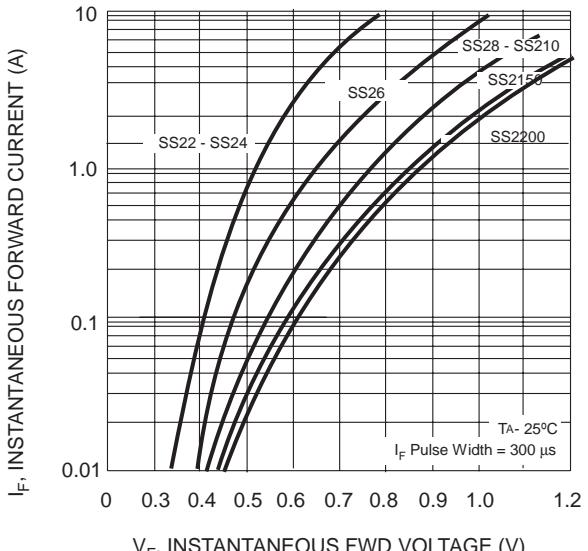
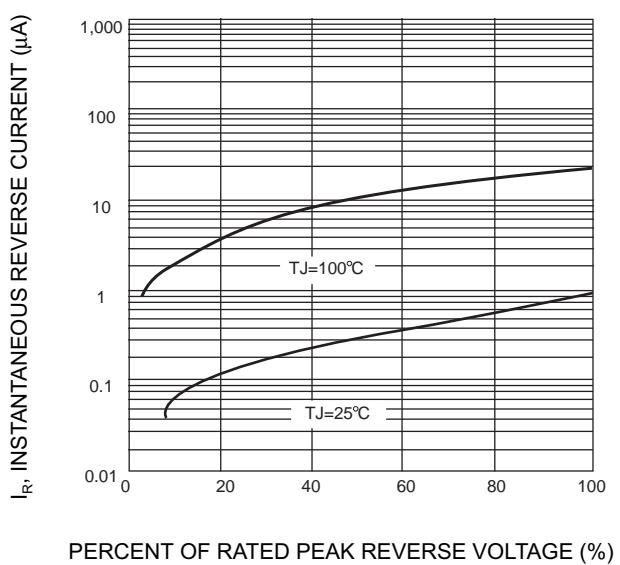


Fig. 4 Typical Reverse Characteristics (per element)



SMA PAD LAYOUT

